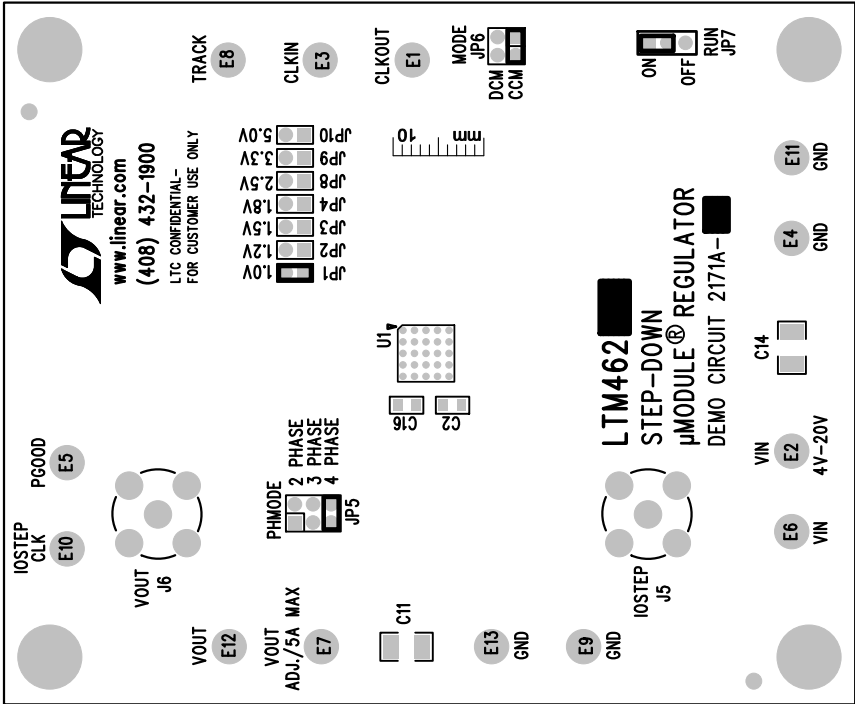
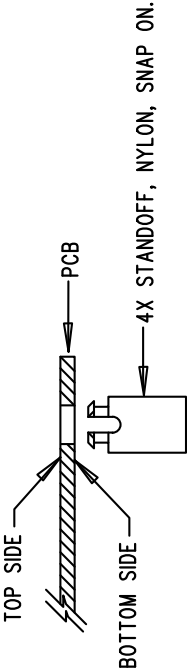



REVISION HISTORY			
ECO	REV	DESCRIPTION	DATE
-	1	PRODUCTION	10-30-13

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPROVALS		 <div>LINEAR TECHNOLOGY</div> <div>1830 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY</div>			
PCB DES.	HZ				
APP ENG.	SAM Y.				
TITLE: TOP ASSEMBLY DRAWING		STEP-DOWN μMODULE® REGULATOR			
		SIZE	IC NO.	LTM4623EY/LTM4625EY	REV.
		N/A		DEMO CIRCUIT 2171A	1
SCALE = NONE		FILENAME: DC2171A-1.PCB			
		SHT 1		OF 2	